Abstract

A method and system for precision micromachining by utilizing X-ray imaging and laser ablation. X-ray is utilized for imaging and locating one or more buried features or defects in semiconductor packages or devices, while laser ablation is accurately targeted at the area of interest to achieve precise and accurate micromachining. X-ray imaging and laser ablation can either occur simultaneously or in turns during the precision micromachining process.

Abstract Figure: FIG. **3b**